

**Thermosettable Adhesive****Abstract**

The invention relates to a thermosettable adhesive comprising a thermosettable  
5 polymer component, a thermoformable polymer component, an effective amount of  
a heat-activatable and/or photoactivatable curing system for curing the  
thermosettable polymer component, and from 0.5 -20 wt.% with respect to the  
mass of the thermosettable adhesive of one or more hydroxides and/or  
hydroxyoxides of Al, Mg and/or Zr.